

**Industry Leading Epoxy Laminate and Prepreg** Tg 180°C Td 340°C Dk 4.04 Df 0.021

IPC-4101 /98 /99 /101 /126 UL - File E41625 Grade PCL-FR-370HR

# 370HR is the industry's "best in class" lead-free compatible product for high-reliability applications across a wide range of markets.

#### **PRODUCT FEATURES**

**Industry Recognition** 

- UL File Number: E41625
- Polyclad<sup>®</sup> Grade PCL-FR-370HR
- Qualified to UL's MCIL Program
- RoHS Compliant

Performance Attributes

CAF resistant

**Processing Advantages** 

- FR-4 process compatible
- UV blocking and AOI fluorescence
- Multiple reflow capable
- HDI technology compatible

#### **PRODUCT AVAILABILITY**

Standard Material Offering: Laminate

• 2 to 125 mil (0.05 to 3.2 mm)

#### Copper Foil Type

- HTE Grade 3
- RTF (Reverse Treat Foil)
- Embedded resistor foil

#### Copper Weight

- $\frac{1}{2}$ , 1 and 2 oz (18, 35 and 70  $\mu$ m) available
- Heavier copper foil available
- Thinner copper foil available

Standard Material Offering: Prepreg

Tooling of prepreg panels

#### Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass

### **ORDERING INFORMATION:**

Contact your local sales representative or contact info@isola-group.com for further information.

370HR laminates and prepregs, deigned by Polyclad, are made using a patented high performance 180°C Tg FR-4 multifunctional epoxy resin system that is designed for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required. We manufacture 370HR laminates and prepregs with high quality E-glass glass fabric for superior Conductive Anodic Filament (CAF) resistance. 370HR provides superior thermal performance with low Coefficient of Thermal Expansion (CTE) and the mechanical, chemical and moisture resistance properties that equal or exceed the performance of traditional FR-4 materials.

370HR is used in thousands of PWB designs and has proven to be best in class for thermal reliability, CAF performance, ease of processing and proven performance on sequential lamination designs.

#### PRODUCT ATTRIBUTES





#### TYPICAL MARKET APPLICATIONS













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## **Typical Values Table**

			Units	Test Method
	Property	Typical Value	Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		180	°C	2.4.25C
Decomposition Temperature (Tg) by TGA @ 5% weight loss		340	°C	2.4.24.6
Time to Delaminate by TMA  A. T260		60	C	2.4.24.0
(Copper removed)	B. T288	30	Minutes	2.4.24.1
Z-Axis CTE	A. Pre-Tg	45	ppm/°C ppm/°C %	2.4.24C
	B. Post-Tg	230		
	C. 50 to 260°C, (Total Expansion)	2.8		
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		0.4	W/m·K	ASTM E1952
Thermal Stress 10 sec @	A. Unetched	_		
288ºC (550.4ºF)	B. Etched	Pass	Pass Visual	2.4.13.1
Dk, Permittivity	A. @ 100 MHz	4.24		2.5.5.3
	B. @ 1 GHz	4.17	_	2.5.5.9
	C. @ 2 GHz	4.04		Bereskin Stripline
	D. @ 5 GHz	3.92		Bereskin Stripline
	E. @ 10 GHz	3.92		Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz	0.0150		2.5.5.3
	B. @ 1 GHz	0.0161	_	2.5.5.9
	C. @ 2 GHz	0.0210	_	Bereskin Stripline
	D. @ 5 GHz E. @ 10 GHz	0.0250	_	2.5.5.5 2.5.5.5
	-	3.0 x 10 <sup>8</sup>		2.5.5.5
Volume Resistivity	A. After moisture resistance B. At elevated temperature	7.0 x 10 <sup>8</sup>	MΩ-cm	2.5.17.1
Surface Resistivity	A. After moisture resistance	3.0 × 10 <sup>6</sup>		
	B. At elevated temperature	$2.0 \times 10^{8}$	ΜΩ	2.5.17.1
Dielectric Breakdown		>50	kV	2.5.6B
Arc Resistance		115	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		54 (1350)	kV/mm (V/mil)	2.5.6.2A
Community of Translation Indian (CTI)		2 (175 240)	Character (Market)	UL 746A
Comparative Tracking Index (CTI)		3 (175-249)	Class (Volts)	ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile		N/mm (lb/inch)	2.4.8C
	copper foil all copper foil >17 µm [0.669 mil]	1.14 (6.5)		2.4.00
	B. Standard profile copper	1.25 (7.0)		2.4.8.2A
	1. After thermal stress 2. At 125°C (257°F)	1.25 (7.0)		2.4.8.3
	3. After process solutions	1.14 (6.5)		2.4.8.3
	A. Length direction	90.0		
Flexural Strength	B. Cross direction	77.0	ksi	2.4.4B
Tensile Strength	A. Length direction	55.9	ksi	
	B. Cross direction	35.6		ASTM D3039
Young's Modulus	A. Length direction	3744	ksi	ACTM D700 15 2
	B. Cross direction	3178		ASTM D790-15e2
Poisson's Ratio	A. Length direction	0.177	_	ACTM D2020
	B. Cross direction	0.171		ASTM D3039
Moisture Absorption		0.15	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		V-0	Rating	UL 94
Relative Thermal Index (RTI)		130	°C	UL 796

#### **NOTES**

Visit our site <a href="http://www.isola-group.com">http://www.isola-group.com</a> for more details.

Revisions:

A: Initial release - 4/17

B: Corrected units for Flexural and Tensile Strength - 8/18

C: Change MOT to RTI 5/19

D: Changed VLP2 to HVLP to align with common industry terms 4/21

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